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(54) **THREE-DIMENSIONAL MICROSTRUCTURES HAVING AN EMBEDDED SUPPORT MEMBER WITH AN APERTURE THEREIN AND METHOD OF FORMATION THEREOF**

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H01P 3/06 (2006.01)

(52) **U.S. Cl.** **333/244**; 29/828

(58) **Field of Classification Search** 333/243, 333/244, 238; 29/828; 174/28
See application file for complete search history.

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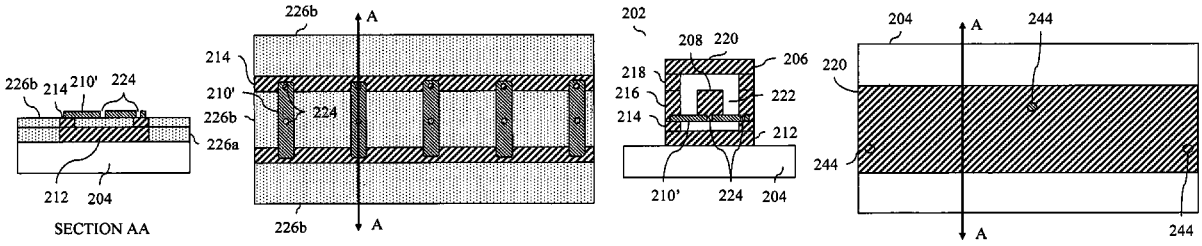
(57) **ABSTRACT**

Provided are three-dimensional microstructures and their methods of formation. The microstructures are formed by a sequential build process and include microstructural elements which are affixed to one another. The microstructures find use, for example, in coaxial transmission lines for electromagnetic energy.

17 Claims, 9 Drawing Sheets